

### Product Change Notification / RMES-04EPMW610

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26-Jun-2023

## **Product Category:**

**Network Synchronization** 

# **PCN Type:**

Manufacturing Change

## **Notification Subject:**

CCB 6122 Final Notice: Qualification of CEL-9240HF10-U as a new mold compound material for ZL80034LDG1, ZL80035LDG1, ZL30833ALDG1 and ZL30934ALDG1 catalog part numbers (CPN) available in 64L VQFN (9x9x1mm) package assembled at ASEM assembly site.

### **Affected CPNs:**

RMES-04EPMW610\_Affected\_CPN\_06262023.pdf RMES-04EPMW610\_Affected\_CPN\_06262023.csv

#### **Notification Text:**

**PCN Status:**Final Notification

PCN Type:Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of CEL-9240HF10-U as a new mold compound material for ZL80034LDG1, ZL80035LDG1, ZL30833ALDG1 and ZL30934ALDG1 catalog part numbers (CPN) available in 64L VQFN (9x9x1mm) package assembled at ASEM assembly site.

### **Pre and Post Change Summary:**

	Pre Change	Post Change					
Assembly Site	ASE Group -Malaysia	ASE Group -Malaysia					
	(ASEM)	(ASEM)					
Wire Material	Au	Au					
Die Attach Material	CRM-1076DS / HR-5104	CRM-1076DS / HR-5104					
Molding Compound Material	G770SFL	CEL-9240HF10-U					
DAP Surface Prep	Dbl Ag ring plated	Dbl Ag ring plated					
Lead-frame Material	C194	C194					

### Impacts to Data Sheet:None

Change ImpactNone

**Reason for Change:**To improve manufacturability by qualifying CEL-9240HF10-U as a new mold compound material.

**Change Implementation Status:**In Progress

Estimated First Ship Date: July 24, 2023 (date code: 2330)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

## **Time Table Summary:**

	April 2023			>	June 2023				July 2023							
Workweek	1 4	1 5	1 6	1 7	1 8		2 2	2 3	24	25	26	2 7	2 8	2 9	3 0	31
Initial PCN Issue Date				Х												
Qual Report Availability											Х					
Final PCN Issue Date											Х					
Estimated Implementation Date															Х	

Method to Identify Change:Traceability code

**Qualification Report:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:** April 04, 2023: Issued initial notification.

June 26, 2023: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on July 24, 2023.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

#### Attachments:

PCN\_RMES-04EPMW610\_Qual\_Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

#### **Terms and Conditions:**

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

ZL80034LDG1 ZL80035LDG1

ZL30833ALDG1

ZL30934ALDG1

Date: Sunday, June 25, 2023